

$\mu_m = 10^{-4} \text{ cm}^2/\text{V}\cdot\text{s}$ $\mu_n = 1450 \text{ cm}^2/\text{V}\cdot\text{s}$

注意长度单位通常是cm!!

$\frac{kT}{q} = V_T = 25.9 \text{ mV}$

$R = 1.6 \times 10^{-19}$

$E_{Si} = 11.9 \times 8.854 \times 10^{-14} \text{ F/cm}$

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零偏

正偏: V_F 正偏

$PIN \text{ 结: } V_{bi} = V_T \ln \left(\frac{N_A N_D}{n_i^2} \right) = V_{bi} - V_F$

$X_D = X_n + X_p = \sqrt{\frac{2 \epsilon_{Si} (V_{bi} - V_F)}{q (N_A + N_D)}}$

$E_{max} = -\frac{q}{\epsilon_{Si}} N_A X_p \text{ 或 } -\frac{q}{\epsilon_{Si}} N_D X_n$

能带: $n: E_F = E_c + kT \ln \left(\frac{N_D}{n_i} \right)$

$= E_{Fi} + kT \ln \left(\frac{N_D}{n_i} \right)$

$p: E_F = E_v - kT \ln \left(\frac{N_A}{n_i} \right)$

$= E_{Fi} + kT \ln \left(\frac{N_A}{n_i} \right)$

泊松方程: $\frac{d^2 \phi}{dx^2} = -\frac{\rho}{\epsilon_{Si}} = -\frac{dE}{dx}$

电容: $C = A \epsilon_{Si} \frac{E_{Si}}{X_D} = AC'$

$(\frac{1}{C'})^2 = f(V_R) = \frac{2(V_{bi} + V_R)}{q \epsilon_{Si} N_D}$

扩散电容: $C = A q \left(\frac{D_n n_{p0} L_p}{U_T} + \frac{D_p p_{n0} L_n}{U_T} \right) \frac{V_F}{U_T}$

雪崩击穿: $V_B = 60 (E_g / 1.1)^{3/4} (N_B / 10^{16})^{-3/4}$

$V_B = V_R$

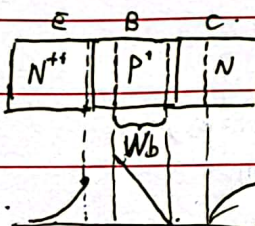
BJT: $B-K$ 反偏 V_R 空间电荷区

NPN 为例: $\alpha_T = 1 - \frac{W_b^2}{2L_b^2}$

$\beta = \frac{1}{1 - \alpha_T} = \frac{1}{1 - \frac{W_b^2}{2L_b^2}}$

$\alpha_0 = \alpha_T$

$\beta_0 = \frac{\alpha_0}{1 - \alpha_0}$



$g_m = \frac{I_c}{V_T}$ $g_{ce} = \frac{g_m}{\beta_0}$

$f_T = \beta_0 f_\beta = \frac{1}{2\pi} \frac{g_m}{C_F + C_{je} + C_{jc} + C_{je}}$

$\tau_F = \tau_B = \frac{W_b^2}{2D_n} = \frac{C_{je}}{g_m}$

$\tau_C = \tau_C (C_{jc} + \frac{C_{je}}{g_m})$

$E-M$ 模型: E, I_c, I_F, I_R

$I_{sc} = I_{sa} \left[\exp \left(\frac{V_{bc}}{V_T} \right) - 1 \right]$

物理模型: 产生复合 E, I_c, I_F, I_R

产生复合 E, I_c, I_F, I_R

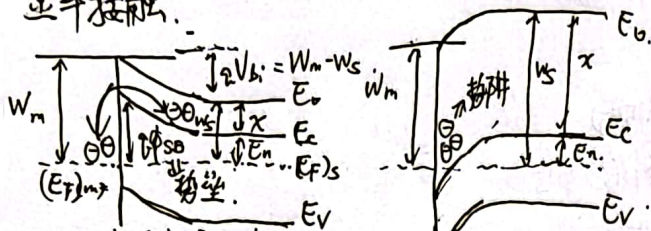
产生复合 E, I_c, I_F, I_R

产生复合 E, I_c, I_F, I_R

产生复合 E, I_c, I_F, I_R



金半接触

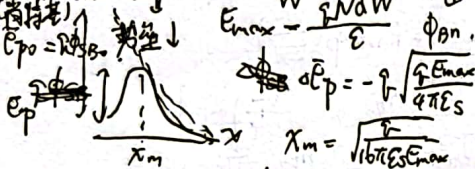


JFET: 内建电压 $V_{po} = \frac{q a^2 N_d}{2 \epsilon_s}$
 $\dots V_p = V_{po} - V_{bi}$

沿金半电导 $G_0 = \frac{2 q N_d \mu_n \epsilon}{L}$ MESFET: $W < a$ 耗尽型
 $W > a$ 增强型
 $W = \sqrt{\frac{\epsilon_s V_{bi}}{q N_d}}$

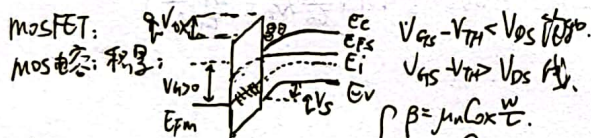
肖特基接触/欧姆/阻挡层
 $W_m > W_s$ 肖特基 $W_m < W_s$ 欧姆
 n 肖特基 欧姆
 p 欧姆 肖特基
 $E_n = E_c - E_f = -kT \ln(\frac{N_d}{N_c})$
 $E_p - E_f - E_v = -kT \ln(\frac{N_a}{N_v})$

肖特基: 耗尽区宽度 $W = \chi_n = \sqrt{\frac{2 \epsilon_s V_{total}}{q N_d}}$ $\frac{1}{C_s} = \frac{2(V_{bi} + V_R)}{q N_d \epsilon}$
 镜像力效应: 感应电荷 $C' = \frac{\epsilon_s}{W}$ $C_s = \frac{q N_d W}{\epsilon}$
 $E_{max} = \frac{\phi_{Bn}}{\epsilon}$
 $C_{po} = \frac{q N_d}{4 \pi \epsilon_s}$
 $\phi_{Bn} = -q \sqrt{\frac{q E_{max}}{4 \pi \epsilon_s}}$
 $\chi_m = \sqrt{\frac{\phi_{Bn}}{16 \pi \epsilon_s E_{max}}}$

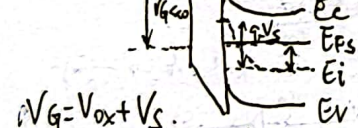


扩散理论: $J = J_0 [\exp(\frac{V_R}{V_T}) - 1]$
 $J_{SD} = q \sqrt{\frac{q N_d V_{total}}{\epsilon_s}} \exp(-\frac{V_{bi}}{V_T})$

热发射理论: $J_{ST} = J_{ST} [\exp(\frac{V_R}{V_T}) - 1]$
 $J_{ST} = R^* T^2 \exp(-\frac{\phi_{Bn}}{V_T})$
 $R^* = 120 \frac{m^2}{m \cdot s}$



MOSFET: $V_{GS} - V_{TH} < V_{DS}$ 线性区
 $V_{GS} - V_{TH} > V_{DS}$ 饱和区
 $\beta = \mu_n C_{ox} \frac{W}{L}$
 $C_{ox} = \frac{\epsilon_{ox}}{t_{ox}}$
 线性: $I_D = \frac{1}{2} \beta (V_{GS} - V_{TH})^2$
 饱和: $I_D = \beta (V_{GS} - V_{TH}) V_{DS} - \frac{1}{2} \beta V_{DS}^2$
 $g_0 = \frac{\partial I_D}{\partial V_{DS}} = \beta (V_{GS} - V_{TH})$
 $Q_{ox} = -\frac{C_{ox}}{t_{ox}} V(x)$



$V_G = V_{ox} + V_s$
 $E_{FS} - E_i = V_B = kT \ln(\frac{N_D}{n_i})$
 $V_B = \frac{kT}{q} \ln(\frac{N_D}{n_i}) = \frac{kT}{q} \ln(\frac{N_A}{n_i})$
 $Q_B = q N_d x_{max} = \sqrt{2 \epsilon_s (q V_B) q N_d}$
 $V_{TH} = 2 V_B + \frac{Q_B}{C_{ox}} (+ V_{FB})$
 $C_{ox} = \frac{\epsilon_{ox}}{t_{ox}}$ $V_{TP} = -2 V_B - \frac{Q_B}{C_{ox}}$
 $V_{FB} = \phi_{ms} - \frac{Q_{ss}}{C_{ox}}$
 $\phi_{ms} = \frac{W_m - W_s}{q}$
 $W_s = x + \frac{q}{2} + q V_B$
 $C_{FB} = \frac{Q_{ox} S}{t_{ox} + \frac{\epsilon_{ox}}{\epsilon_s} \sqrt{U_T \frac{\epsilon_s}{q N_d}}}$

